Features

- Low-Forward Voltage Drop
- Guard Ring Construction for Transient Protection
- Low Capacitance
- Ultra-Small Surface-Mount Package
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **This part is qualified to JEDEC standards (as references in AEC-Q) for High Reliability. https://www.diodes.com/quality/product-definitions/**
- **An automotive-compliant part is available under separate datasheet (SDM20U30LPQ)**

Mechanical Data

- Package: X1-DFN1006-2
- Package Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: Cathode Dot
- Terminals: Finish—NiPdAu Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 e4
- Weight: 0.001 grams (Approximate)

X1-DFN1006-2

Top View

Bottom View

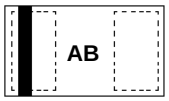
Ordering Information (Note 4)

Part Number	Package	Packing	
		Qty.	Carrier
SDM20U30LP-7	X1-DFN1006-2 (Pitch 4mm)	3000	Tape & Reel
SDM20U30LP-7B	X1-DFN1006-2 (Pitch 2mm)	10000	Tape & Reel

Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

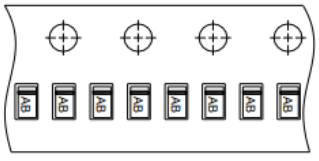
Marking Information

Marking &Packing

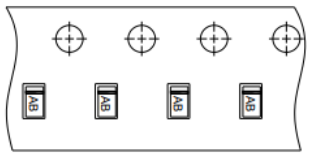


Top View
Bar Denotes Cathode Side

AB = Product Type Marking Code
AB = LM or LM



SDM20U30LP-7B



SDM20U30LP-7

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	30	V
RMS Reverse Voltage	$V_{R(RMS)}$	21	V
Maximum (Peak) Forward Current	I_{FM}	200	mA
Peak Forward Surge Current 8.3ms Half Sine	I_{FSM}	1.0	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation	P_D	250	mW
Thermal Resistance, Junction to Ambient Air (Note 5)	$R_{\theta JA}$	400	°C/W
Operating and Storage Temperature Range	T_J, T_{STG}	-65 to +125	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Conditions
Reverse Breakdown Voltage (Note 6)	$V_{(BR)R}$	30	—	—	V	I_R = 150µA
Forward Voltage Drop	V_F	—	—	350 575	mV	I_F = 20mA I_F = 200mA
Peak Reverse Current (Note 6)	I_R	—	—	150 30	µA µA	V_R = 30V V_R = 10V
Total Capacitance	C_T	—	20	—	pF	V_R = 0V, f = 1.0MHz
Reverse Recovery Time	t_{RR}	—	3	—	ns	I_F = I_R = 10mA $I_{R(REC)}$ = 1mA R_L = 100Ω

Notes: 5. Device mounted on FR-4 substrate PCB, with minimum recommended pad layout.
6. Short duration pulse test used to minimize self-heating effect.

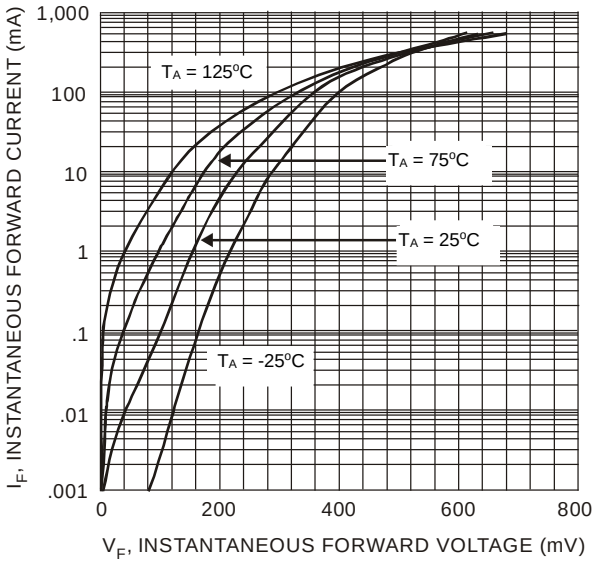


Fig. 1 Typical Forward Characteristics

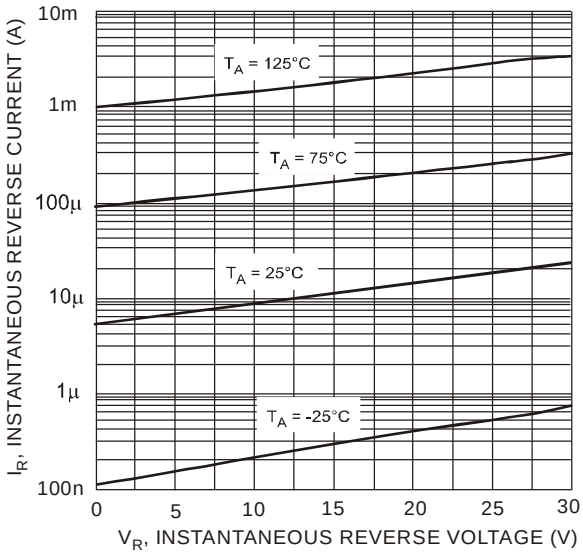


Fig. 2 Typical Reverse Characteristics

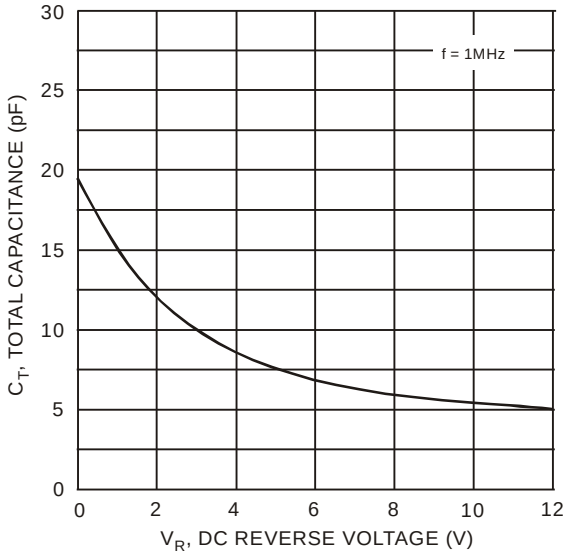


Fig. 3 Total Capacitance vs. Reverse Voltage

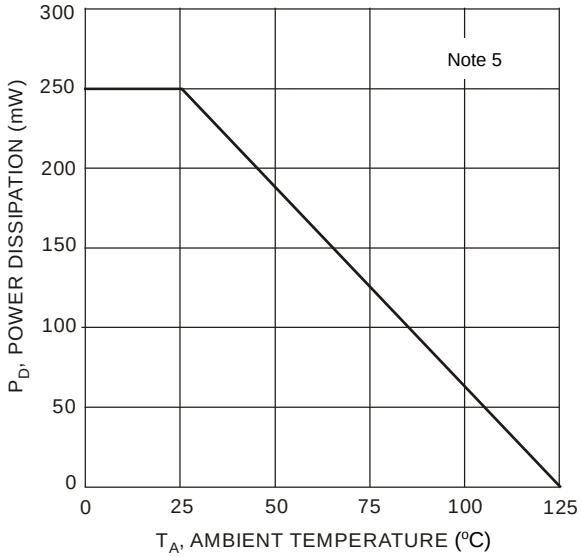
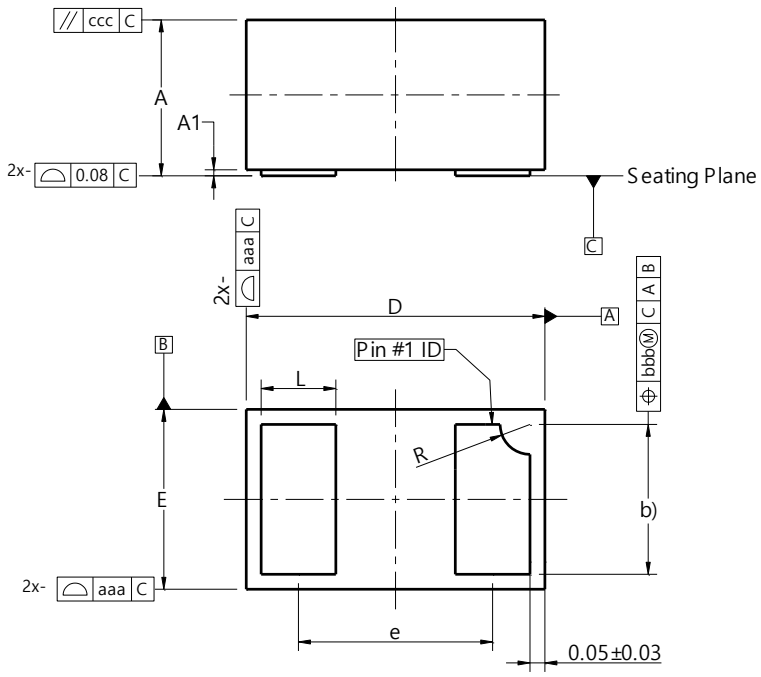


Fig. 4 Power Derating Curve

Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

X1-DFN1006-2

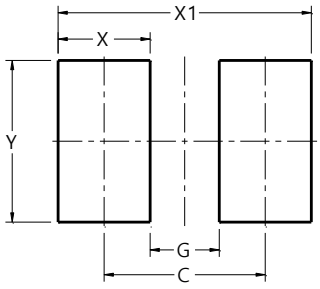


X1-DFN1006-2			
Dim	**Min**	**Max**	**Typ**
A	0.47	0.53	0.50
A1	0.00	0.05	0.03
b	0.45	0.55	0.50
D	0.95	1.075	1.00
E	0.55	0.675	0.60
e	--	--	0.65
L	0.20	0.30	0.25
R	0.05	0.15	0.10
aaa	0.15		
bbb	0.05		
ccc	0.05		
All Dimensions in mm			

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

X1-DFN1006-2



Dimensions	Value (in mm)
C	0.70
G	0.30
X	0.40
X1	1.10
Y	0.70

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